



<b>Title of Change:</b>	Qualification of Sumitomo mold compound from G700HC to G700HF.
<b>Proposed first ship date:</b>	28 September 2016
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <MohdHezri.AbuBakar@onsemi.com>
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <AhmadFaris.Dzulkipli@onsemi.com>
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <cheanching.sim@onsemi.com>
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
<b>Change Part Identification:</b>	Affected parts will be identified with a date code of WW38'16 or later
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____

**Change Sub-Category(s):**
 Manufacturing Site Change/Addition  
 Manufacturing Process Change

 Material Change  
 Product specific change

 Datasheet/Product Doc change  
 Shipping/Packaging/Marking  
 Other: \_\_\_\_\_
**Sites Affected:**
 All site(s)     not applicable

 ON Semiconductor site(s) :  
 ON Seremban, Malaysia

 External Foundry/Subcon site(s)
**Description and Purpose:**

This is a Final Change Notification to announce the change in mold compound on selected devices in DPAK package from Sumitomo G700HC to G700HF. This change is to improve delamination at post area.

**Reliability Data Summary:**

#	Test	Name	Test Condition	Read points	NTDV20N06T4G	NVD5490NLT4G	NVD5117PLT4G	NVD6824NLT4G
1	AC-PC	Autoclave + PC	121°C/100% RH/15psig	96 Hrs	NA	0/84	0/84	0/84
2	TC-PC	Temperature Cycling + PC	Ta = -55/150° C	1000 Cyc	0/84	0/84	0/84	0/84
3	UHAST-PC	Unbias High Accelerated Stress Test + PC	121°C/100% RH/15psig	96 Hrs	0/84	NA	NA	NA
4	HAST-PC	Highly Accelerated Stress Test + PC	Ta= +130° C, RH = 85%, PSIG= 18.8,	96 Hrs	NA	NA	0/84	NA
5	H3TRB – PC	High Humidity High Temp Rev Bias + Preconditioning	Ta=85°C, 85% RH, 80% rated or 100V max	1008 Hrs	0/84	0/84	NA	0/84
6	IOL-PC	Intermittent Operating Life + PC	Ta=+25°C, delta Tj=100°C	15000 Cyc	0/84	0/84	0/84	0/84
7	HTRB	High Temp Reverse Bias	TA = 175°C	1008 Hrs	0/84	0/84	0/84	0/84
8	HTGB	High Temp Gate Bias	TA = 175°C	1008 Hrs	0/84	0/84	0/84	0/84
9	HTSL	High Temperature Storage Life	Ta = 175° C	1008 Hrs	0/84	0/84	0/84	0/84
10	RSH	Resistance to Solder Heat	260 C Immersion	Result	0/30	0/30	0/30	0/30

**AEC -1 pager attachment:**

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s



**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
NTDV5805NT4G	NVD6824NLT4G
NVD4805NT4G	NVD6824NLT4G
NVD4806NT4G	NVD6824NLT4G
NVD4809NHT4G	NVD6824NLT4G
NVD4809NT4G	NVD6824NLT4G
NVD4813NHT4G	NVD6824NLT4G
NVD4815NT4G	NVD6824NLT4G